

# Material Declaration Report



Package Type:	DIP24
Pericom Package Code:	P24(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	2125.056
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	NA
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	Feb,05.2009

## Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	1626.662	J	Silica Fused	60676-86-0	80.20	1304.58292
			Epoxy, Cresol Novolac	29690-82-2	10.00	162.66620
			Phenol Novolac	9003-35-4	5.00	81.33310
			Antimony Trioxide	1309-64-4	2.00	32.53324
			Brominated Epoxy Resin	40039-93-8	2.50	40.66655
			Carbon Black	1333-86-4	0.30	4.87999
LEAD FRAME	495.504		Cu	7440-50-8	97.41	482.68283
			Fe	7439-89-6	2.35	11.64434
			P	7723-14-0	0.08	0.40879
			Zn	7440-66-6	0.13	0.61938
			Pb	7440-5-3	0.03	0.14865
			Silver	7740-22-4	--	--
TERMINATION PLATING	1.570		Tin	7440-31-5	99.90	1.56843
			Impurity	Proprietary	0.10	0.00157
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.600		Resin	Trade secret	15.00	0.09000
			Silver	7440-22-4	80.00	0.48000
			2-Butoxyethyl acetate	112-07-2	5.00	0.03000
GOLD WIRE	0.370		Au	7440-57-5	99.99	0.36996
			Other materials	Proprietary	0.01	0.00004

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

## 3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

## ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC  and  China RoHS Directive SJ/T11363-2006	<b>Declaration Statement:</b>	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.  
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.